PRODUCT ADVANTAGE

High Reliability
Minimize Induced Stresses
Enhance Mechanical Resistance
Fast Flow
Fast Low Temperature Cure
Room Temperature Underfilling

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OUR THREE PILLARS

1. EXCEEDING PERFORMANCE SPECIFICATIONS
2. MAXIMIZING PRODUCTIVITY
3. LOWERING PROCESS COST

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YINCAE® Underfill Materials Family

**Featured Underfills**

- **SMT 88U**: super-fast flow and fast low temperature (88°C) cure capillary underfill
- **SMT 158D**: highly conductive (> 5 W/mK) diamond filled capillary underfill
- **SMT 158F**: no resin bleeding, fast flow and fast cure capillary underfill
- **SMT 158HA**: fast flow and low temperature slow cure high purity liquid epoxy underfill
- **SMT 158N**: non-flow, high purity liquid epoxy designed to replace corner and edge bonding adhesives

**Underfill Materials**

- SMT 158 shows thermocycling improvement over competitors underfills (thermocycling conditions: -65°C to 150°C, 1 cycle)
- SMT 158 products have proven to resist failure from temperature and humidity changes (3% test: 85°C / 85% RH)
- SMT 88UH shows a high number of drops before failure (drop height: 60 cm, concrete floor)

**Summary**

- **YINCAE® Underfill Materials** are a set of capillary underfills, room temperature underfills, and wafer level underfills.

- The **SMT 158 capillary underfill series** is a collection of capillary flow nano underfills. The products in this series offer rapid curing, fast flow, and can be used for CSP, BGA, PoP, LGA, and flip chip applications.

- The **SMT 88 series** is a collection of underfill materials offering room temperature underfilling, super-fast flow, and super-fast low temperature cure.

Contact YINCAE at info@yincae.com for detailed specifications & customization for your specific product requirements.